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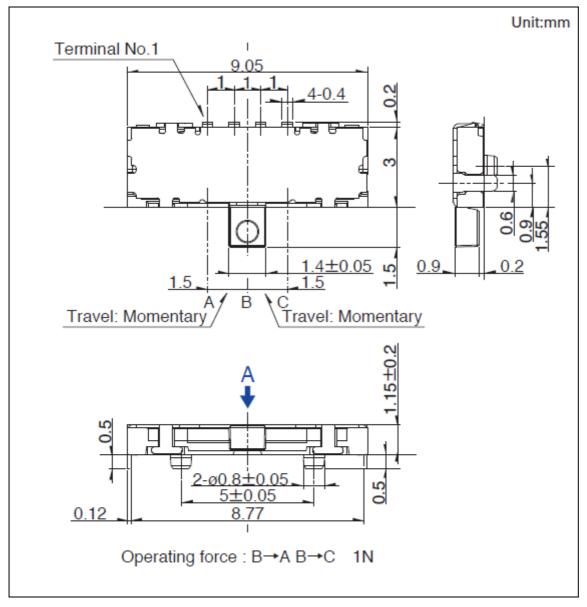
## Recoil Type for Single-side and Both-sides SSAG Series

Travel			1.5mm
Actuator directions			Horizontal
Poles			1
Positions			3
Operating force			1N (Recoil side)
Changeover timing			Not specified
Soldering			Reflow
Operation			Double-side recoil
Shape of frame leg			For PC board insert
Location lug			With
Operating temperature range			-10°C to +60°C
Rating (max.)/(min.) (Resistive load)			10mA 5V DC/50µA 3V DC
Electrical performance	Contact resistance (Initial performance/After lifetime)		200m $\Omega$ max./500m $\Omega$ max.
	Insulation resistance		100MΩ min. 100V DC
	Voltage proof		100V AC for 1 minute
Mechanical performance	Terminal strength		3N for 1 minute
	Actuator strength	Operating direction	10N
		Pulling direction	10N
Durability	Operating life without load		100,000 cycles 500m $\Omega$ max.
	Operating life with load (at max. rated load)		100,000 cycles 500m $\Omega$ max.
Environmental performance	Cold		−40°C 96h
	Dry heat		85℃ 96h
	Damp heat		40°C, 90 to 95%RH 96h
Minimum order unit (pcs	s.) Japan		4,000
	Export		16,000

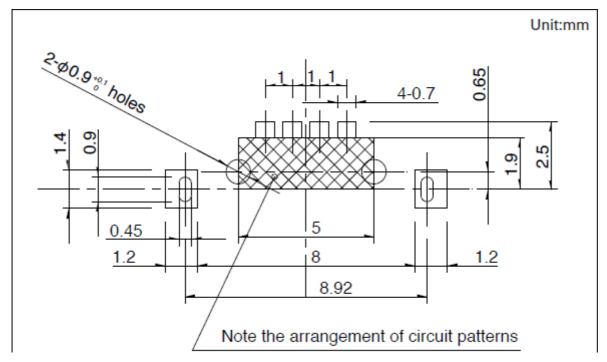
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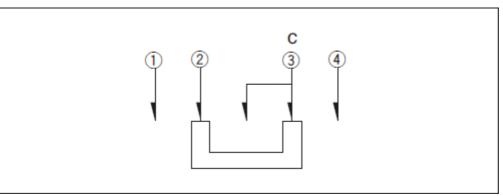
Land Dimensions



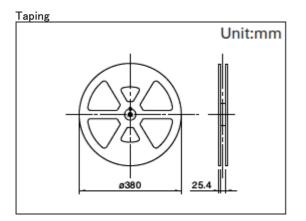
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#### **Packing Specifications**



Number of packages (pcs.)	1 reel	4,000
	1 case / Japan	8,000
	1 case / export packing	: 16,000
Tape width (mm)		24
Export package measurements (mm)		428 × 413 × 172

### Soldering Conditions

Example of Reflow Soldering Condition

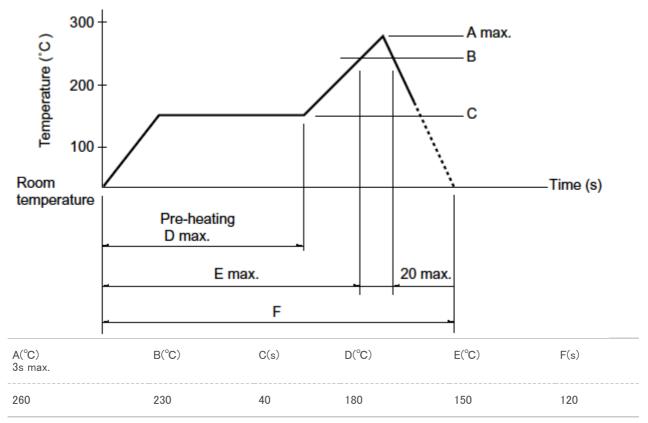
1. Heating method

Double heating method with infrared heater.

2. Temperature measurement Thermocouple 0.1 to 0.2  $\Phi$  CA (K) or CC (T) at soldering portion (copper foil surface). A heat resisting tape should be used

for fixed measurement.

3. Temperature profile



(1) The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc. The above-stated conditions shall also apply to switch surface temperatures.

(2) Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

#### **Reference for Hand Soldering**

Soldering temperature	350±5°C
Soldering time	3s max.

#### Notes are common to this series/models.

- 1. This site catalog shows only outline specifications. When using the products, please obtain formal specifications for supply.
- 2. Please place purchase orders per minimum order unit (integer).